

ABSTRACT

"Improvements in or relating to solders"

A substantially lead-free solder with enhanced properties comprises from 88.5% to 93.5% tin; from 3.5% to 4.5% silver; from 2.0% to 6.0% indium; and from 0.3% to 1.0% copper. The solder may also comprise up to 0.5% of an anti-oxidant or anti-skinning additive. A solder embodying the invention finds particular utility in wave-soldering processes where it may be used as a direct replacement for conventional tin/lead solder.